Universitatea Tehnică din Cluj-Napoca
Facultatea de Electronică, Telecomunicaţii şi Tehnologia Informaţiei
Departamentul de Electronică Aplicată
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LISTA
lucrărilor ştiinţifice în domeniul disciplinelor din postul didactic

A – Teza de doctorat

„Analiza integrităţii alimentării pe plachetele electronice cu circuit imprimat”
Conducător ştiinţific : Prof.dr.ing. Dan Pitica
Domeniul Inginerie electronică şi telecomunicaţii
Universitatea Universitatea Tehnică din Cluj-Napoca.
Susţinere publică: *Decembrie 2011*.

B – Cărţi şi capitole în cărţi publicate în ultimii 10 ani

CĂRŢI

1. Ovidiu Pop, **Raul Fizeşan,** *Computer Aided Design.* Editura U.T. Press, Cluj-Napoca, 2016.
2. **Raul Fizeşan**, Ovidiu Pop, Gabriel Chindriş, *Computer Aided Design: laboratory applications* **,** Editura U.T. Press, Cluj-Napoca , 2015
3. Ovidiu Pop, **Raul Fizeşan**, Gabriel Chindriş, *Proiectare asistată de calculator: aplicaţii* , Editura U.T. Press, Cluj-Napoca, 2013, ISBN 978-973-662-856-6

CAPITOLE DE CARTE

1.

C – Lucrări indexate ISI/BDI publicate în ultimii 10 ani

c1) Articole / studii publicate în reviste de specialitate de circulaţie internaţională recunoscute (cotate ISI)

1. Viman, L., Daraban, M**., Fizesan, R.,** & Iuonas, M**.**. XpertTrack: Precision Autonomous Measuring Device Developed for Real Time Shipments Tracker. *Sensors*, 16(3), 355, 2016.

c2) Studii publicate la conferinţe indexate în baze de date internaţionale de referinţă în domeniul ..... (DBLP, ACM, IEEE, SCOPUS)[1]

[1] indexate în:
[IEEE] - IEEE Xplore (http://ieeexplore.ieee.org/Xplore/guesthome.jsp)
[ACM] - ACM portal (http://portal.acm.org)
[DBLP] - (http://www.informatik.uni-trier.de)
[SCOPUS] - (http://www.scopus.com)

2. Alexandru-Andrei, A., & **Fizesan, R**. (2024, October). Resistive and Capacitive Sensors Driver for Irrigation Applications. In 2024 IEEE 30th International Symposium for Design and Technology in Electronic Packaging (SIITME) (pp. 81-86). IEEE.
3. Ursutiu, T., Chindris, G., **Fizesan, R**., Taut, M. and Taut, A., 2023, October. PCB Design for Reduced Thermal Drift for Current Measurements Through Shunt Resistors. In *2023 IEEE 29th International Symposium for Design and Technology in Electronic Packaging (SIITME)* (pp. 308-311). IEEE.
4. Daraban, M., Corches, C., **Fizesan, R**. and Chindris, G., 2022, October. Real-Time Embedded Framework Debugger. In *2022 IEEE 28th International Symposium for Design and Technology in Electronic Packaging (SIITME)* (pp. 36-39). IEEE.
5. Fodor, A., R. Jánó, and **R. T. Fizeșan**. "Characterization of the V-Model Approach in Thermal Design Process." *2019 IEEE 25th International Symposium for Design and Technology in Electronic Packaging (SIITME)*. IEEE, 2019.
6. **Fizeșan, R., &** Pop, O. (2018). PI Timing Measurements in High Speed Flash Memory Embedded Systems**.** *24th International Symposium for Design and Technology of Electronics Packages – SIITME,* Octombrie 2018, Iasi, Romania, IEEE. 10.1109/SIITME.2018.8599211 **[IEEE] [ISI Web of Knowledge]**
7. Pop, O., Taut, A., Grama, A., **Fizesan, R**., & Ceuca, E. (2017, May). PSpice discharge model for simulation circuits with lead-acid battery. In *Electronics Technology (ISSE), 2017 40th International Spring Seminar on* (pp. 1-4). IEEE., 10.1109/ISSE.2017.8000943 **[IEEE] [ISI Web of Knowledge]**
8. Pop, O., **Fizesan, R.**, Taut, A., & Ceuca, E. (2016, May). Influence of switching frequency on active and reactive load power of resonant converters. In *Electronics Technology (ISSE), 2016 39th International Spring Seminar on* (pp. 328-331). IEEE. 10.1109/ISSE.2016.7563214 **[IEEE] [SCOPUS]**
9. **Fizeșan, R.,** Pop, O. & Tăut, A. (2015). Why the mounting inductance is important in designing a Power Distribution System?**.** *21th International Symposium for Design and Technology of Electronics Packages – SIITME,* Octombrie 2015, Brașov, Romania, IEEE. http://dx.doi.org/10.1109/SIITME.2015.7342309 **[IEEE] [SCOPUS]**
10. Fărcaș, C., Ciocan, I., Pălaghiță, N. & **Fizeșan, R.** (2015). Weekly Electronic Pills Dispenser with Circular. *21th International Symposium for Design and Technology of Electronics Packages – SIITME,* Octombrie 2015, Brașov, Romania, IEEE. http://dx.doi.org/10.1109/SIITME.2015.7342308 **[IEEE] [SCOPUS]**
11. Tăut, A**.,** Chindriș, G., Dărăban, M., Pop, O. & **Fizeșan, R.** (2015). The Mathematical Analysis to Control Power Transfer in Resonant Power Converters**.** *21th International Symposium for Design and Technology of Electronics Packages – SIITME,* Octombrie 2015, Brașov, Romania, IEEE. http://dx.doi.org/10.1109/SIITME.2015.7342335 **[IEEE] [SCOPUS]**
12. Dărăban, M., **Fizeșan, R.**, Pitică, D. & Viman, L. (2015). A SPICE Analysis on How PDNs Can Benefit From Crosstalk Avoidance Code. *In ISSE 2015 - 38th International Spring Seminar on Electronics Technology*, 6-10 May, Eger, Hungary, IEEE. http://dx.doi.org/10.1109/ISSE.2015.7248037 **[IEEE] [SCOPUS]**
13. **Fizeșan, R.,** & Pop, O. (2014). Parameterized PI SPICE platforms for AC and time-domain simulations. In *Power Engineering Conference (UPEC), 2014 49th International Universities* (pp. 1-4). IEEE. http://dx.doi.org/10.1109/UPEC.2014.6934832 **[IEEE] [SCOPUS]**

14. **Fizeşan, R**., Pitică, D & Pop, O. (2013). 2D and 3D Representations of the Noise in a PCB using Analytical Methods. *ISSE 2013 – 36nd International Spring Seminar on Electronics Technology.*, Alba Iulia, Romania. http://dx.doi.org/10.1109/ISSE.2013.6648285 **[IEEE] [SCOPUS]**
15. **Fizesan, R. T.** (2013). Reliable Power Integrity Analysis using MATLAB. *Acta Technica Napocensis*, *54*(1), 19.
16. **Fizesan, R**., & Pitica, D. (2012). Power integrity design tips to minimize the effects of mounting inductance of decoupling capacitors. In *Optimization of Electrical and Electronic Equipment (OPTIM), 2012 13th International Conference on* (pp. 36-41). IEEE. http://dx.doi.org/10.1109/OPTIM.2012.6231953 **[IEEE] [SCOPUS]**
17. **Fizesan, R**., & Pop, O. (2012). A MATLAB tool to optimize the selection of the decoupling capacitors in a PDN. In *Design and Technology in Electronic Packaging (SIITME), 2012 IEEE 18th International Symposium for*(pp. 223-226). IEEE. http://dx.doi.org/10.1109/SIITME.2012.6384380 **[IEEE] [SCOPUS]**
18. **Fizeşan, R.,** & Pitică, D. (2011). The Impact of the Planes Parameters on the Noise of a Power Distribution Network. *ISSE 2011 – 34nd International Spring Seminar on Electronics Technology.* 11-15 May, Tatranska Lomnica, Slovakia. http://dx.doi.org/10.1109/ISSE.2011.6053951
19. **Fizesan, R.,** & Pitica, D. (2011). Pre-layout power integrity analysis in the design flow of a PCB. In *Design and Technology in Electronic Packaging (SIITME), 2011 IEEE 17th International Symposium for* (pp. 77-80). IEEE. http://dx.doi.org/10.1109/SIITME.2011.6102690 **[IEEE] [SCOPUS]**
20. **Fizeşan, R.,** & Pitică, D. (2011). Efficient Strategies to Optimize a Power Distribution Network. *Acta Technica Napocensis Electronics and Telecommunications*.
21. **Fizeşan, R**., & Pitică, D. (2010). Simulation for power integrity to design a PCB for an optimum cost. *SIITME 2010 – 16th International Symposium for Design and Technology of Electronic Packages*. 23-26 September, Piteşti, România. http://dx.doi.org/10.1109/SIITME.2010.5653491 **[IEEE] [SCOPUS]**
22. **Fizeşan, R.,** & Pitică, D. (2010). MATLAB Platform to Calculate the Transfer Impedance of Power and Ground Planes. *ISSE 2010 – 33rd International Spring Seminar on Electronics Technology*. 12-16 May, Warsaw, Poland. http://dx.doi.org/10.1109/ISSE.2010.5547342 **[IEEE] [SCOPUS]**
23. Man, L., Fărcaş C., & **Fizeşan, R.,** (2010). Packaging and Thermal Analysis of Power Electronics Modules, *ISSE 2010 – 33rd International Spring Seminar on Electronics Technology*. 12-16 May, Warsaw, Poland. http://dx.doi.org/10.1109/ISSE.2010.5547296 **[IEEE] [SCOPUS]**
24. **Fizeşan, R.,** Pitică, D., & Man, L. (2009). Power Integrity Analysis and Bypass Capacitors Selection Using FDM on a Printed Circuit Board. *ISSE 2009 – 32nd International Spring Seminar on Electronics Technology*, IEEE Catalog Number: CFP09509, ISBN: 978-1-4244-4260-7. 13-17 May, Brno, Czech Republic. http://dx.doi.org/10.1109/ISSE.2009.5207051 **[IEEE] [SCOPUS]**
25. **Fizeşan, R.,** & Pitică, D. (2009). Circuit Models for Power/Ground Planes on PCBs Using SPICE Method. *15th International Symposium for Design and Technology of Electronics Packages – SIITME*, Issue 1, Conference Proceedings CD, ISBN: 978-1-4244-50330309. 17-20 September, Gyula, Hungary. http://dx.doi.org/10.1109/SIITME.2009.5407382 **[IEEE] [SCOPUS]**

D – Lucrări publicate în ultimii 10 anii în reviste şi volume de conferinţe cu referenţi (neindexate)

- Reviste

1. **Fizeşan, R.** (2009). Bypass Capacitor in Power Distribution Systems: An Overview. *Novice Insight in Electronics, Communications and Information Technology*.
2. **Fizeşan, R.** (2009). Design Methodology for Bypass Capacitor Selection in Power Distribution Systems. *Novice Insight in Electronics, Communications and Information Technology*.
3. **Fizeşan, R.,** & Pitică, D. (2009). Board Planes Analysis for Power Integrity. *Novice Insight in Electronics, Communications and Information Technology*.

- Selecţie cu maximum 20 lucrări în volume de conferinţe

1.

E – Brevete obţinute pentru întreaga activitate

1.
2.

F – Contracte de cercetare (2013-2019)

1. Contract de cercetare cu mediul social şi de afaceri, nr. 22379/8.11.2006, Continental GmBH Germany– Universitatea Tehnică din Cluj-Napoca: "ITEC-Conti Cooperation" – director de proiect Gabriel Chindris
2. Contract de cercetare cu mediul social şi de afaceri, nr. 7705/11.06.2014, SC Continental Automotive SRL Timisoara, – Universitatea Tehnică din Cluj-Napoca: "Sisteme de testare HW & SW in automotive", 2014, Director grant Gabriel Chindris
3. Contract de cercetare cu mediul social şi de afaceri, nr. 12268. /25.05.2017, SC Continental Automotive Systems SRL Sibiu – Universitatea Tehnică din Cluj-Napoca: "Dezvoltarea sistemelor embedded HW & SW in automotive", 2017

Data Semnătura